

RELIABILITY MONITOR

PROCESS: 0.6 μ m Double Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS21352	A4	MAR '01	26769	0103	ATK (Anam, K)	DN033071AAA	LQFP	48	224	6

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS21352	A4	MAR '01	26770	0103	ATK (Anam, K)	DN033071AAA	LQFP	336	77	0
DS21352	A4	MAR '01	26770	0103	ATK (Anam, K)	DN033071AAA	LQFP	1000	76	0
DS21352	A4	JUN '01	27346	0103	ATP (Anam, PI)	DN033071AAA	LQFP	336	77	0

TOTALS FOR: 0.6 μ m Double Poly, Double Metal (Ti/T) FAIL RATE (Fits): 515 DEVICE HRS: 1.42E+07 6

RELIABILITY MONITOR

PROCESS: 0.6 μ m Single Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS80CH11	A4	MAR '01	27058	0103	ATK (Anam, K)	DN029182AAA	LQFP	48	235	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS80CH11	A4	MAR '01	26786	0103	ATK (Anam, K)	DN029182AAA	LQFP	336	77	0

TOTALS FOR: 0.6 μ m Single Poly, Double Metal (Ti/Ti) FAIL RATE (Fits): 199 DEVICE HRS: 4.60E+06 0

RELIABILITY MONITOR

PROCESS: 0.6 µm Single Poly, Single Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS5002	C5	JAN '01	26508	0047	ATK (Anam, K)	DN028766AAD	MQFP	48	198	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2118M	B1	JUN '01	27114	0117	ATK (Anam, K)	DN101149AAD	SSOP	336	77	0
DS2118M	B1	JUN '01	27114	0117	ATK (Anam, K)	DN101149AAD	SSOP	336	77	0
DS2118M	B1	JUN '01	27114	0117	ATK (Anam, K)	DN101149AAD	SSOP	1000	77	0
DS2118M	B1	JUN '01	27114	0117	ATK (Anam, K)	DN101149AAD	SSOP	1000	77	0
DS5002	C5	APR '01	26901	0112	ATK (Anam, K)	DN030363AAA	MQFP	336	77	0
DS5002	C6	JUL '01	27364	0122	ATK (Anam, K)	DN042297AAA	MQFP	336	80	0
DS5002	C5	JAN '01	26509	0047	ATK (Anam, K)	DN028766AAD	MQFP	336	77	0
DS5002	C5	JAN '01	26509	0047	ATK (Anam, K)	DN028766AAD	MQFP	1000	77	0
DS5002	C5	APR '01	26901	0112	ATK (Anam, K)	DN030363AAA	MQFP	1000	77	0
DS80C320	C5	APR '01	26894	0111	CPS (ChipPac, China)	DH040746AA	PDIP	336	77	0

TOTALS FOR: 0.6 µm Single Poly, Single Metal (Ti/Ti) FAIL RATE (Fits): 17 DEVICE HRS: 5.31E+07 0

RELIABILITY MONITOR

PROCESS: 0.8 μ m Double Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2154	A2	MAR '01	26762	0106	ATK (Anam, K)	DN040708AA-	LQFP	48	232	2

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2154	A2	MAR '01	26763	0106	ATK (Anam, K)	DN040708AA-	LQFP	336	77	0
DS2154	A2	MAR '01	26763	0106	ATK (Anam, K)	DN040708AA-	LQFP	1000	77	0
DS2154	A2	JUN '01	27101	0107	Stats	DC040702AA-	LQFP	336	77	0

TOTALS FOR: 0.8 μ m Double Poly, Double Metal (Ti/T) FAIL RATE (Fits): 216 DEVICE HRS: 1.44E+07 2

RELIABILITY MONITOR

PROCESS: 0.8 μ m Single Poly, Double Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1803	A2	MAY '00	25438	0013	OSEP	DE951193AAF	SOIC	48	227	0
DS1803	A2	FEB '00	25191	0007	OSEP	DE946274AAA	SOIC	48	226	0
DS1803	A2	AUG '00	25925	0034	OSEP	DE023435AAB	SOIC	48	221	1

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1803	A2	FEB '00	25192	0007	OSEP	DE946274AAA	SOIC	336	75	0
DS1803	A2	MAY '00	25439	0013	OSEP	DE951193AAF	SOIC	336	76	0
DS1803	A2	AUG '00	25926	0034	OSEP	DE023435AAB	SOIC	1000	77	0
DS1803	A2	FEB '00	25192	0007	OSEP	DE946274AAA	SOIC	1000	62	0

TOTALS FOR: 0.8 μ m Single Poly, Double Metal FAIL RATE (Fits): 36 DEVICE HRS: 5.66E+07 1

RELIABILITY MONITOR

PROCESS: 0.8 µm Single Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1302	A3	MAR '01	26749	0105	CPS (ChipPac, China)	DH036622AB	PDIP	48	234	0
DS1803	A2	FEB '01	26609	0105	OSEP	DE047362AAB	SOIC	48	232	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1302	A3	MAR '01	26750	0105	CPS (ChipPac, China)	DH036622AB	PDIP	1000	77	0
DS1803	A2	AUG '00	25926	0034	OSEP	DE023435AAB	SOIC	336	77	0
DS1803	A2	MAY '00	25439	0013	OSEP	DE951193AAF	SOIC	1000	65	0

TOTALS FOR: 0.8 µm Single Poly, Double Metal (Ti/Ti) FAIL RATE (Fits): 26 DEVICE HRS: 3.54E+07 0

RELIABILITY MONITOR

PROCESS: 0.8 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1232	C2-L	JAN '01	26435	0051	ATP (Anam, PI)	DK038265AAC	SOIC	48	233	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1232	C2-L	JAN '01	26436	0051	ATP (Anam, PI)	DK038265AAC	SOIC	336	77	0
DS1232	C2-L	JAN '01	26436	0051	ATP (Anam, PI)	DK038265AAC	SOIC	1000	76	0
DS1232	C2-L	APR '01	26864	0105	OSEP	DE045054ABB	SOIC	336	77	0
DS1620	D1	JUN '01	27093	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	336	77	0
DS1620	D1	JUN '01	27093	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	1000	77	0
DS21S07	C1-	FEB '01	26588	0047	Carsem S	DM035532AF	TSSOP	336	77	0
DS21S07	C1-	FEB '01	26588	0047	Carsem S	DM035532AF	TSSOP	1000	77	8

TOTALS FOR: 0.8 μ m Single Poly, Single Metal FAIL RATE (Fits): 103 DEVICE HRS: 9.14E+07 8

RELIABILITY MONITOR

PROCESS: 1.2 µm Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1267	A2	FEB '00	25175	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	48	226	0
DS1267	A1	FEB '01	26571	0102	Carsem S	DM039441AB	TSSOP	48	234	0
DS1869	A3	JUN '00	25543	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	48	236	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1267	A2	FEB '00	25176	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	336	77	0
DS1267	A1	MAY '01	26979	0104	ATP (Anam, PI)	DK043419AAB	TSSOP	336	75	0
DS1267	A2	FEB '00	25176	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	1000	77	0
DS1267	A1	FEB '01	26572	0102	Carsem S	DM039441AB	TSSOP	336	77	0
DS1267	A1	FEB '01	26572	0102	Carsem S	DM039441AB	TSSOP	1000	76	0
DS1869	A3	JUN '00	25544	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	336	76	0
DS1869	A3	JUN '00	25544	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	1000	75	0

TOTALS FOR: 1.2 µm Single Poly, Single Metal FAIL RATE (Fits): 17 DEVICE HRS: 5.46E+07 0

RELIABILITY MONITOR

PROCESS: 2.0 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2175	D1	JAN '01	26422	0046	ATP (Anam, PI)	DE033119AAB	SOIC	48	233	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2175	D1	JAN '01	26423	0046	ATP (Anam, PI)	DE033119AAB	SOIC	336	77	0
DS2175	D1	APR '01	26883	0050	ATP (Anam, PI)	DK036683AB	SOIC	336	77	0

TOTALS FOR: 2.0 μ m Single Poly, Single Metal FAIL RATE (Fits): 42 DEVICE HRS: 2.20E+07 0

RELIABILITY MONITOR

PROCESS: 5.0 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2108	B7	FEB '01	26579	0051	ATK (Anam, K)	DN041061AAE	SOIC	48	234	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2108	B7	FEB '01	26580	0051	ATK (Anam, K)	DN041061AAE	SOIC	336	77	0
DS2108	B7	FEB '01	26580	0051	ATK (Anam, K)	DN041061AAE	SOIC	1000	77	0
DS2108	B7	MAY '01	26986	0111	ATP (Anam, PI)	DK101048AAC	SOIC	336	77	0

TOTALS FOR: 5.0 μ m Single Poly, Single Metal FAIL RATE (Fits): 63 DEVICE HRS: 1.47E+07 0